

# PESD3V3U1UA; PESD3V3U1UB; PESD3V3U1UL

Ultra low capacitance unidirectional ESD protection diodes

Rev. 01 — 30 October 2008

Product data sheet

## 1. Product profile

### 1.1 General description

Ultra low capacitance unidirectional ElectroStatic Discharge (ESD) protection diodes in small Surface-Mounted Device (SMD) plastic packages designed to protect one signal line from the damage caused by ESD and other transients.

Table 1. Product overview

Type number	Package		Package configuration
	NXP	JEITA	
PESD3V3U1UA	SOD323	SC-76	very small
PESD3V3U1UB	SOD523	SC-79	ultra small and flat lead
PESD3V3U1UL	SOD882	-	leadless ultra small

### 1.2 Features

- Unidirectional ESD protection of one line
- ESD protection up to 9 kV
- Ultra low diode capacitance:  $C_d = 2.6$  pF
- IEC 61000-4-2; level 4 (ESD)
- Very low leakage current:  $I_{RM} = 1$  nA
- AEC-Q101 qualified

### 1.3 Applications

- USB interfaces
- Cellular handsets and accessories
- 10/100/1000 Mbit/s Ethernet
- Portable electronics
- FireWire
- Communication systems
- High-speed data lines
- Computers and peripherals
- Subscriber Identity Module (SIM) card protection
- Audio and video equipment

### 1.4 Quick reference data

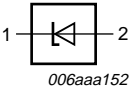
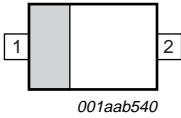
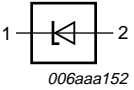
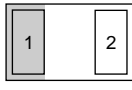
Table 2. Quick reference data

$T_{amb} = 25$  °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{RWM}$	reverse standoff voltage		-	-	3.3	V
$C_d$	diode capacitance	$f = 1$ MHz; $V_R = 0$ V	-	2.6	3.1	pF

## 2. Pinning information

**Table 3. Pinning**

Pin	Description	Simplified outline	Graphic symbol
<b>PESD3V3U1UA; PESD3V3U1UB</b>			
1	cathode	[1]	 006aaa152
2	anode	 001aab540	
<b>PESD3V3U1UL</b>			
1	cathode	[1]	 006aaa152
2	anode	 Transparent top view	

[1] The marking bar indicates the cathode.

## 3. Ordering information

**Table 4. Ordering information**

Type number	Package		
	Name	Description	Version
PESD3V3U1UA	SC-76	plastic surface-mounted package; 2 leads	SOD323
PESD3V3U1UB	SC-79	plastic surface-mounted package; 2 leads	SOD523
PESD3V3U1UL	-	leadless ultra small plastic package; 2 terminals; body 1.0 × 0.6 × 0.5 mm	SOD882

## 4. Marking

**Table 5. Marking codes**

Type number	Marking code
PESD3V3U1UA	QT
PESD3V3U1UB	T8
PESD3V3U1UL	XZ

**5. Limiting values**

**Table 6. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-55	+150	°C
$T_{stg}$	storage temperature		-65	+150	°C

**Table 7. ESD maximum ratings**

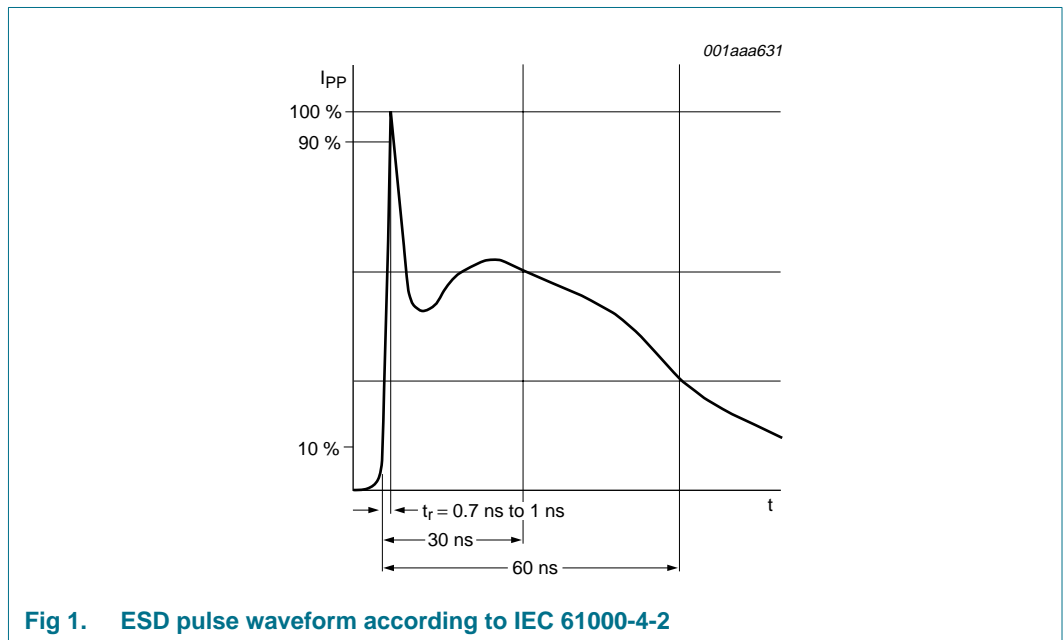
*$T_{amb} = 25\text{ °C}$  unless otherwise specified.*

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{ESD}$	electrostatic discharge voltage	IEC 61000-4-2 (contact discharge)	[1]	-	9 kV
		MIL-STD-883 (human body model)	-	10	kV

[1] Device stressed with ten non-repetitive ESD pulses.

**Table 8. ESD standards compliance**

Standard	Conditions
IEC 61000-4-2; level 4 (ESD)	> 8 kV (contact)
MIL-STD-883; class 3 (human body model)	> 4 kV



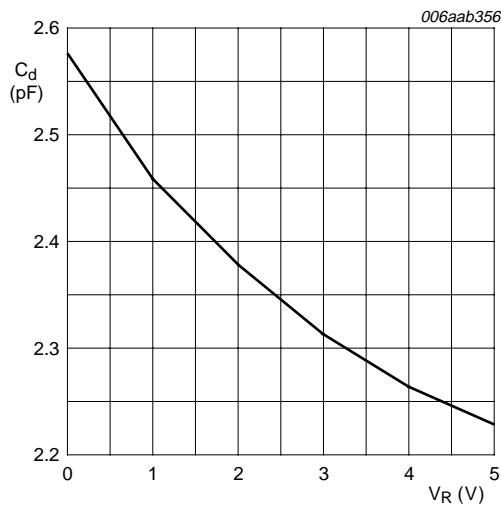
**Fig 1. ESD pulse waveform according to IEC 61000-4-2**

## 6. Characteristics

**Table 9. Characteristics**

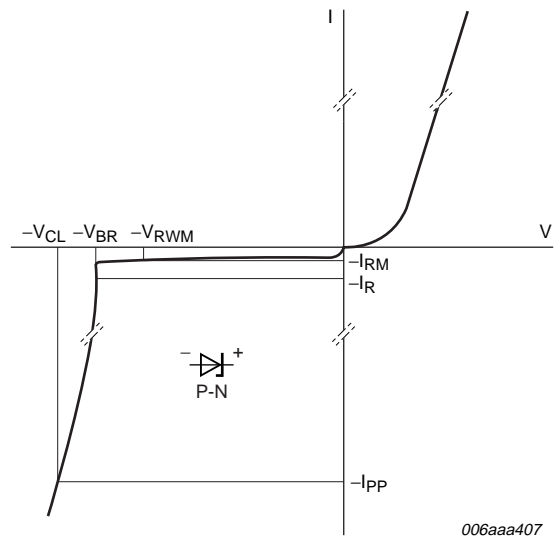
$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{RWM}$	reverse standoff voltage		-	-	3.3	V
$I_{RM}$	reverse leakage current	$V_{RWM} = 3\text{ V}$	-	1	100	nA
$V_{BR}$	breakdown voltage	$I_R = 5\text{ mA}$	4.5	5.6	6.8	V
$C_d$	diode capacitance	$f = 1\text{ MHz}; V_R = 0\text{ V}$	-	2.6	3.1	pF
$r_{dif}$	differential resistance	$I_R = 5\text{ mA}$	-	-	100	$\Omega$



$f = 1\text{ MHz}; T_{amb} = 25\text{ }^{\circ}\text{C}$

**Fig 2. Diode capacitance as a function of reverse voltage; typical values**



**Fig 3. V-I characteristics for a unidirectional ESD protection diode**

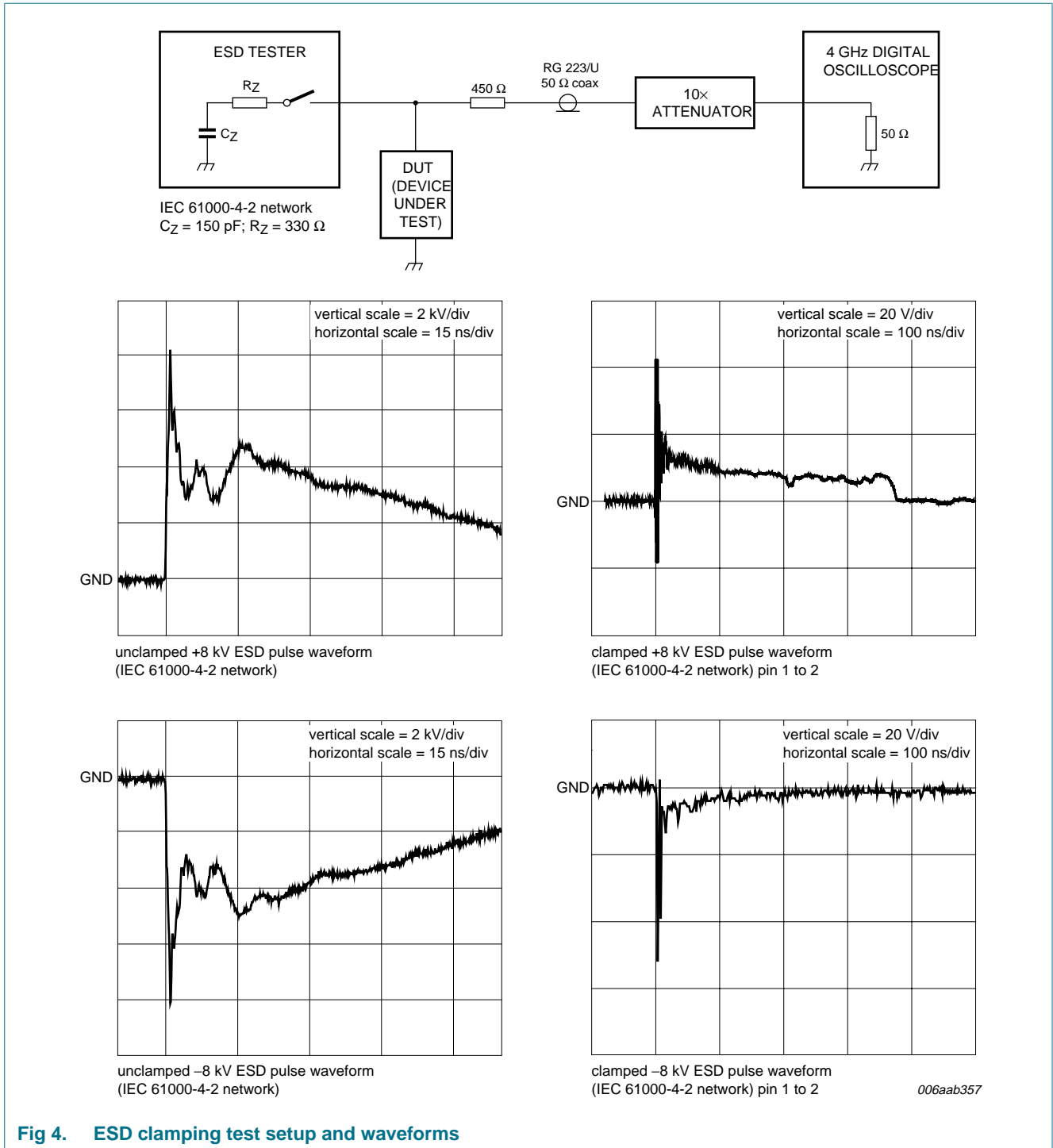


Fig 4. ESD clamping test setup and waveforms

## 7. Application information

The PESD3V3U1Ux series is designed for the protection of one unidirectional data or signal line from the damage caused by ESD. The devices may be used on lines where the signal polarities are either positive or negative with respect to ground.

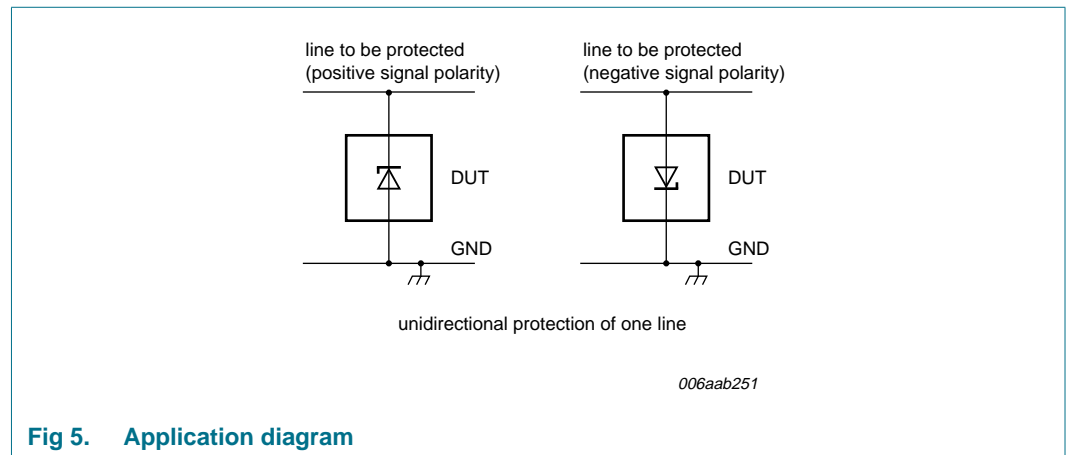


Fig 5. Application diagram

### Circuit board layout and protection device placement

Circuit board layout is critical for the suppression of ESD and Electrical Fast Transient (EFT). The following guidelines are recommended:

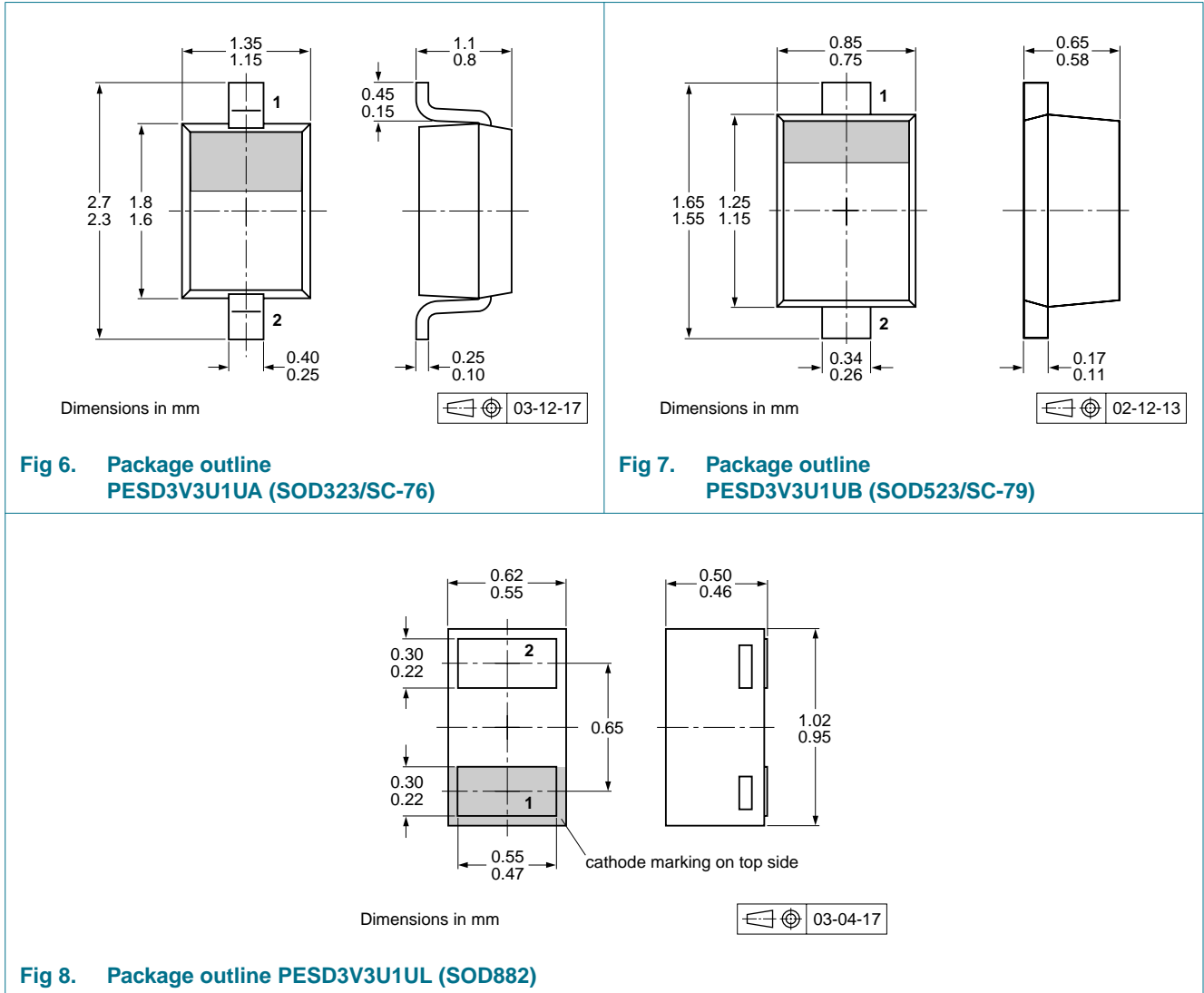
1. Place the device as close to the input terminal or connector as possible.
2. The path length between the device and the protected line should be minimized.
3. Keep parallel signal paths to a minimum.
4. Avoid running protected conductors in parallel with unprotected conductors.
5. Minimize all Printed-Circuit Board (PCB) conductive loops including power and ground loops.
6. Minimize the length of the transient return path to ground.
7. Avoid using shared transient return paths to a common ground point.
8. Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

## 8. Test information

### 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

**9. Package outline**



**10. Packing information**

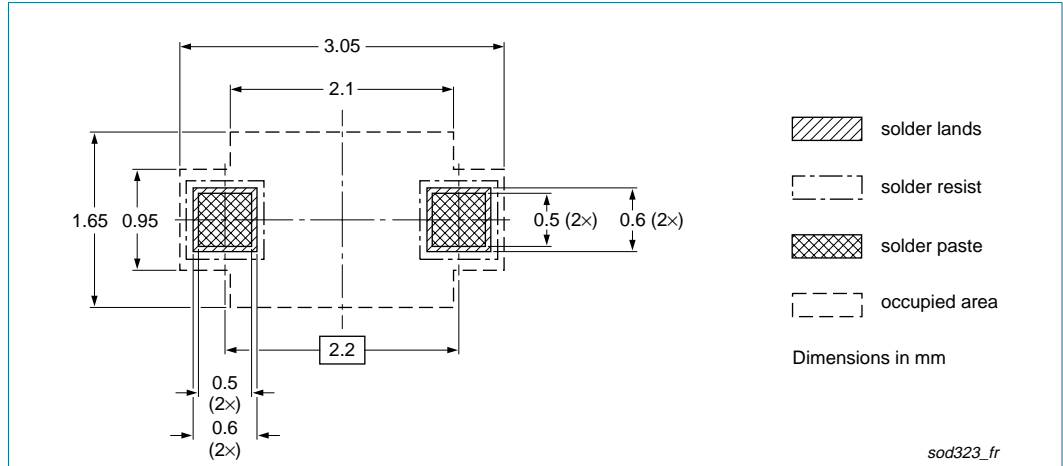
**Table 10. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

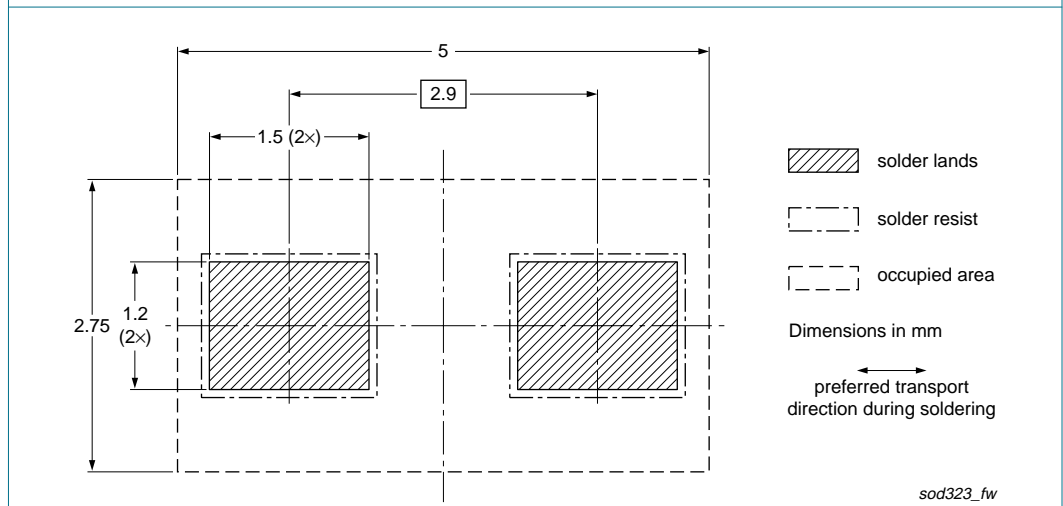
Type number	Package	Description	Packing quantity		
			3000	8000	10000
PESD3V3U1UA	SOD323	4 mm pitch, 8 mm tape and reel	-115	-	-135
PESD3V3U1UB	SOD523	2 mm pitch, 8 mm tape and reel	-	-315	-
		4 mm pitch, 8 mm tape and reel	-115	-	-135
PESD3V3U1UL	SOD882	2 mm pitch, 8 mm tape and reel	-	-	-315

[1] For further information and the availability of packing methods, see [Section 14](#).

**11. Soldering**

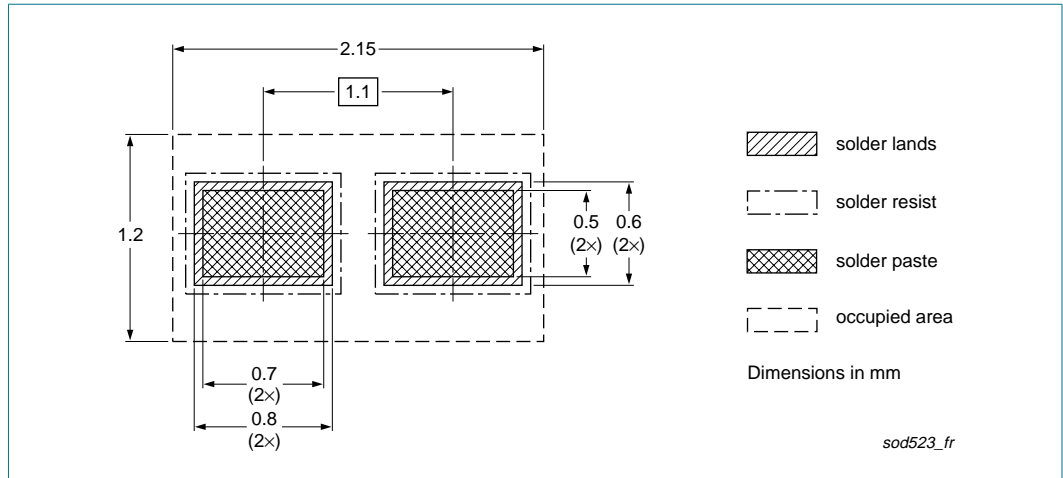


**Fig 9. Reflow soldering footprint PESD3V3U1UA (SOD323/SC-76)**



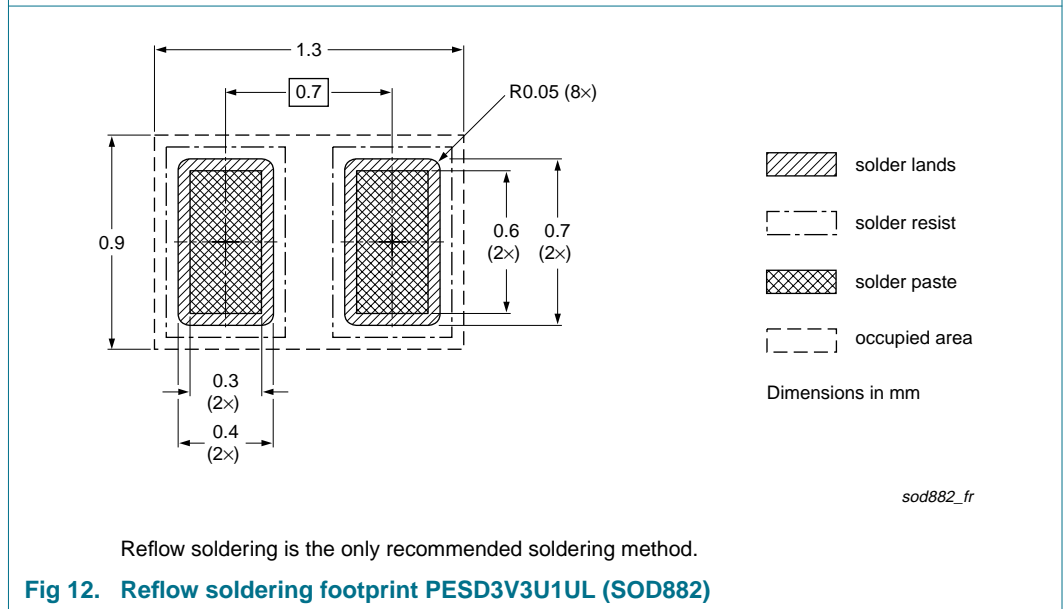
**Fig 10. Wave soldering footprint PESD3V3U1UA (SOD323/SC-76)**





Reflow soldering is the only recommended soldering method.

**Fig 11. Reflow soldering footprint PESD3V3U1UB (SOD523/SC-79)**



Reflow soldering is the only recommended soldering method.

**Fig 12. Reflow soldering footprint PESD3V3U1UL (SOD882)**

## 12. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PESD3V3U1UA_UB_UL_1	20081030	Product data sheet	-	-

## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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Date of release: 30 October 2008

Document identifier: PESD3V3U1UA\_UB\_UL\_1